



(0,50 mm) .0197"

QTH SERIES

QTH-060-07-F-D-A

QTH-030-01-L-D-A

QTH-090-01-C-D-A

HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTH

Insulator Material:

Liquid Crystal Polymer



Terminal Material:

Phosphor Bronze



Plating:

Au or Sn over 50µ" (1,27 µm) Ni

Current Rating:

Contact: 1.0A per contact @ 30°C

Temperature Rise

Ground Plane:

7.8A per ground plane @ 30°C

Temperature Rise

Operating Temp Range:

-55°C to +125°C

Voltage Rating:

125 VAC (5 mm Stack Height)

Max Cycles:

100

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (030-060)

(0,15 mm) .006" max (090)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

APPLICATION SPECIFIC OPTION

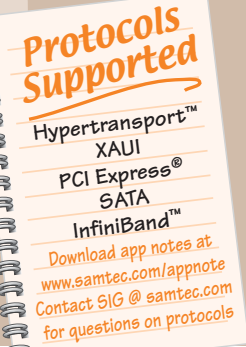
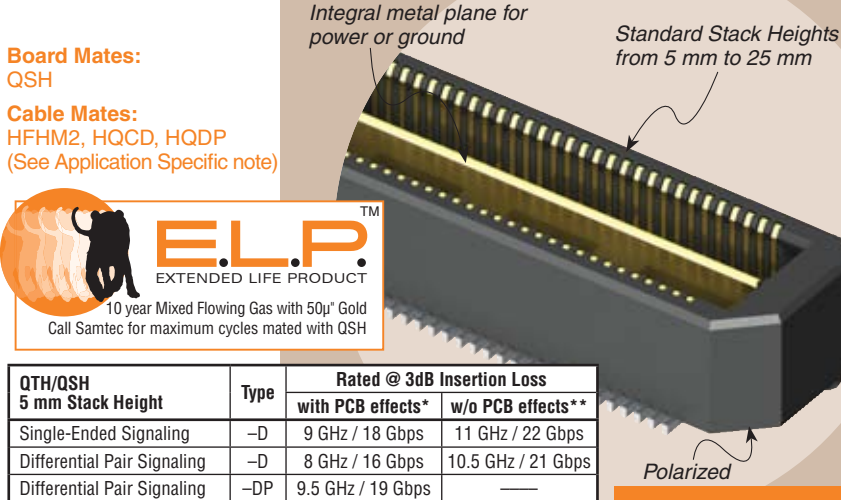
- 14 mm, 15 mm, 22 mm and 30 mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76 µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount & Guide Posts
- 80(-DP), 120, 150 positions per row
- Retention Option Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QSH

Cable Mates:
HFHM2, HQCD, HQDP
(See Application Specific note)



QTH/QSH 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	11 GHz / 22 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	10.5 GHz / 21 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps	—

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.
Performance data for other stack heights and complete test data available at www.samtec.com?QTH or contact sig@samtec.com

ALSO AVAILABLE

Board Spacing Standoffs. See SO Series.

QTH	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-030, -060, -090 (60 total pins per bank = -D)	Specify LEAD STYLE from chart	-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails	-D = Single-Ended		-K = (7,00 mm) .275" DIA Polyimide film Pick & Place Pad (N/A with -05 & -07 lead style)
	-020, -040, -060 (20 pairs per bank = -D-DP)		-L = 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails	-D-DP = Differential Pair (-01 only)		-TR = Tape & Reel (-090 positions maximum)
			-C* = Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails			-L = Latching Option (-01 lead style only) (N/A on -060 (-D-DP), -080, -090 & -120)

-01 & -02

-03 thru -07

QTH LEAD STYLE	A	HEIGHT WITH QSH*
-01	(4,27) .168	(5,00) .197
-02	(7,26) .286	(8,00) .315
-03	(10,27) .404	(11,00) .433
-04	(15,25) .600	(16,00) .630
-05	(18,26) .718	(19,00) .748
-07	(24,24) .954	(25,00) .984

*Processing conditions will affect mated height.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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